

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S82	144898	(via via\$hole through\$hole through adj hole interposer pin BGA pad) same (locat\$4 arrang\$5 re\$arrang\$5 distribut\$4) same (wiring interconnect\$4 routing bond)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:12
S83	34014	(compensat\$4 adjust\$4 rotation) same ("IC" chip semiconductor) same (position location)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:13
S84	2341	S82 and S83	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:13
S85	71	S84 and routing near10 channel	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:14
S86	1	S85 and (716/1,8-15.ccls. 438/6,25,26,106-113.ccls.)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:18
S87	148	S84 and (716/1,8-15.ccls. 438/6,25,26,106-113.ccls.)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:18
S88	101	S87 and @ad<="20041101"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:20
S89	17	S88 and "BGA"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:20
S90	1422676	(via via\$hole through\$hole through adj hole interposer pin BGA pad) same (geometr \$4 location position)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:22

S91	94	S88 and S90	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:23
S92	32	S91 and bond near wire	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:23
S93	18	S91 and (design near5 rule)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 11:24
S94	14	("4864514"   "5155065"   "5465217"   "5498767"   "5608638"   "5661669").PN. OR ("6357036").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/07 12:33
S95	23	("5155065").URPN.	USPAT	OR	ON	2009/01/07 12:49
S96	2844	(variable same bond same (position location))	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/07 13:00
S97	12	S84 and S96	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/07 13:00
S103	13437	(mov\$\$ adjust\$4 rotation) same ("IC" chip semiconductor) same (position location) same (via via\$hole through\$hole through adj hole interposer pin BGA pad)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 14:35
S104	12	S82 and S97	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/07 14:35
S106	3	(bond near wire) near10 simulat\$4 same (fluctuation deviation variation variance variable)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 12:48
S107	1222	(bond near wire) same (fluctuation deviation variation variance variable)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 13:02
S108	22	S107 and simulat\$4 near10 (data information)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 13:02

S109	102708	(chip die device component) with (position location) same (fluctuation deviation variation variance variable)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 14:26
S110	121	S107 and S109	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 14:27
S111	8	S110 and simulat\$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 14:27
S112	1083	(Goto near Akihiro or Matsushima near Hironori or Ogawa near Hiroshige or Matsuda near Yoshio).inv.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 12:55
S113	309	(Goto near Akihiro or Matsushima near Hironori or Ogawa near Hiroshige or Matsuda near Yoshio).inv.	US-PGPUB; USPAT	OR	ON	2009/07/01 12:56
S114	820	((variable fluctuat\$4 variation deviation) near10 (interposer ball\$pad pad contact via \$hole through\$hole) near10 (position location)).clm.	US-PGPUB; USPAT	OR	ON	2009/07/01 12:58
S115	1	S113 and S114	US-PGPUB; USPAT	OR	ON	2009/07/01 12:58
S116	10355	716/1,4-5,18.ccls. 703/13-14.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 12:58
S117	1	S114 and S116	US-PGPUB; USPAT	OR	ON	2009/07/01 12:58
S118	850	((variable fluctuat\$4 variation deviation) near10 (chip component) near10 (position location)).clm.	US-PGPUB; USPAT	OR	ON	2009/07/01 12:59
S119	19	S114 and S118	US-PGPUB; USPAT	OR	ON	2009/07/01 12:59
S120	12220	716/1,4-5,12-15,18.ccls. 703/13-14.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 13:01
S121	15	S118 and S120	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 13:01

S123	16	("20040128630"   "20060094222"   "4342090"   "4980971"   "5189707"   "5792580"   "6118670"   "6198976"   "6205636"   "6461938"   "6537835"   "6617678"   "6718626"   "7052968"   "7132359"   "7341887").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/07/05 14:04
S124	1	("6225143").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/07/05 14:35
S127	12865	(chip die) same (tolerance off \$set deviation variation) same substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/05 14:48
S128	6782	S127 and align\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/05 14:49
S129	4658	S128 and @ad<="20041102"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/05 14:49
S130	15	S129 and bond\$wir\$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/05 14:49
S132	1708	S127 same align\$6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/05 14:51
S133	1179	S132 and @ad<="20041102"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/05 14:51

7/7/2009 1:08:58 PM

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